STATEMENT OF POLICY

The Corporation is constantly originating and exploring new ideas and the commercial adaptation of such ideas in order to improve its products and add profitable ones to its line.

Such new ideas may be patented or otherwise protected by the Corporation, and may be incorporated into our products or business procedures. Such new ideas may also be undergoing further development or may be already planned for future release. These ideas, already known to the Corporation, may be similar to ideas and suggestions submitted to the Corporation by others. In order to prevent possible misunderstandings, and to safeguard the interest of both the submitting party and the Corporation, a policy has been established that all ideas and suggestions are submitted to the Corporation only under the conditions set forth on the reverse side hereof.

When these conditions are agreed to, as evidenced by the signing of the attached Agreement, the idea or suggestion may be submitted to the Corporation. The Corporation’s only obligation with respect to such idea or suggestion will be to review same to the extent appropriate in the Corporation’s sole judgement and thereupon to state the Corporation’s interest therein. In order to fully understand the idea or suggestion and permit an appropriate evaluation of it, all submissions must be complete and in writing. Such submissions must include sketches or drawings and sufficient descriptive material to permit one skilled in the art to fully appreciate the idea or suggestion submitted, and may take the form, for example, of a patent application including only the specification and drawings. No oral disclosures will be accepted and no papers submitted to the Corporation can be returned. The submitter should therefore retain a copy of all material submitted as well as the second copy of this Agreement.

The conditions set forth therein also apply to any additional or supplemental material submitted which relates to any previous submission.

It must also be understood that the Corporation cannot agree to hold your submission in confidence for the reason, among others, that the Corporation may have to disclose the submission to various employees and at times to vendors not in our direct employ, in order to fully evaluate the submission and because agreements to hold in confidence have been found to entail other obligations not intended by either the submitter or the Corporations.

Therefore, the submitter discloses his idea with the understanding that he will rely only upon his rights under the patent laws of the United States and under no other obligation except as specifically set out therein.
AGREEMENT

I have read the attached “Statement of Policy,” PS-71, and understand that the Corporation is willing to consider certain ideas and suggestions which may be presented to it, but the Corporation will consider my submission only under the following conditions:

1. The Corporation is considering my submission only at my request.

2. The submission creates in the Corporation no obligation to treat the ideas or suggestions disclosed hereby in confidence and no obligation of any kind is assumed by or may be implied against the Corporation unless and until a formal written agreement has been entered into and then the obligation shall be only as is expressed in the formal written agreement.

3. I hereby represent and warrant that I have the right to disclose the idea or suggestion; that I have the right to make the present Agreement; that there are no outstanding agreements, either written, oral, or implied, which are inconsistent herewith: and that, unless disclosed otherwise, no other party has a property interest in the idea or suggestion submitted.

4. I do not hereby give the Corporation any rights under any patents I now have or may later obtain covering my submission, but I do hereby, in consideration of the Corporation examining my submission, release it from any liability in connection with my submission or any liability because of the use of any portion thereof, except such liability as may accrue under valid patents now or thereafter issued.

I am agreeable to those conditions and ask that pursuant thereto, you consider my submission for:

________________________________________________________________________

________________________________________________________________________

________________________________________________________________________(Identify briefly-Attach disclosure and sketches or drawings)

I am employed by: __________________________________________________________

Signed: ____________________________

Address: ____________________________

Date: ________________________________

Witnessed: __________________________

Date: ________________________________